

REV.	LOGS	DESCRIPTION	DATE	DRAWN
04	△	change layout	02-03-06	XUD PING
05	△	change Operating Temperature: -40°C to +105°C Tin plating: -40°C to +105°C Solder plating: -40°C to +105°C	2007.01.25	丁敏
06	△	CHANGE VIEW DIM	2007.05.15	黃美君
07	△	ADD Dim Tolerance	2007.05.15	黃美君

**Specifications**

Current Rating: 1Amp  
 Insulation Resistance: 1000MΩ Min.  
 Dielectric Withstanding: 300V AC/DC  
 Contact Resistance: 20mΩ Max.

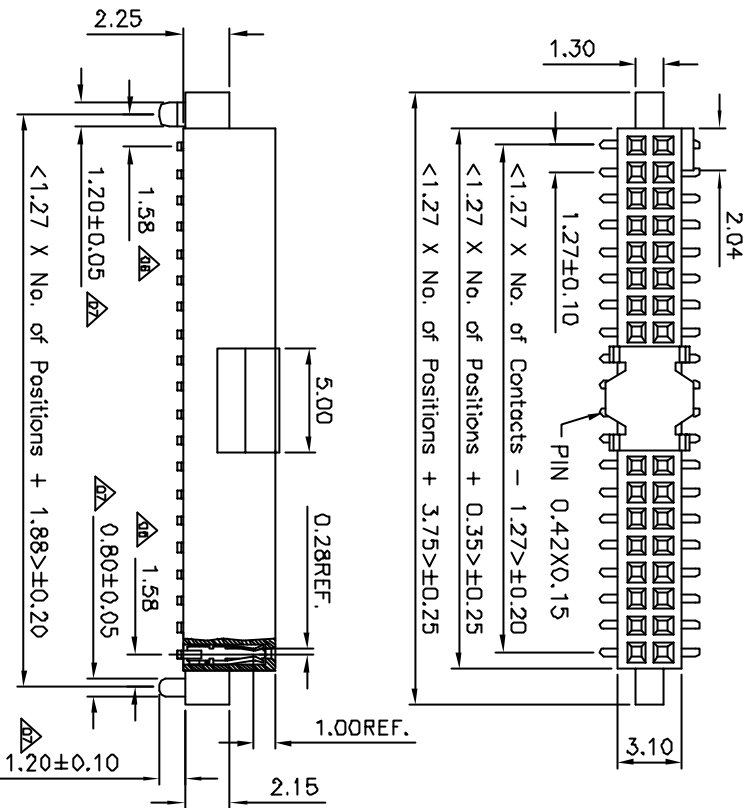
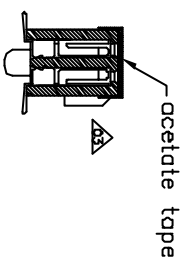
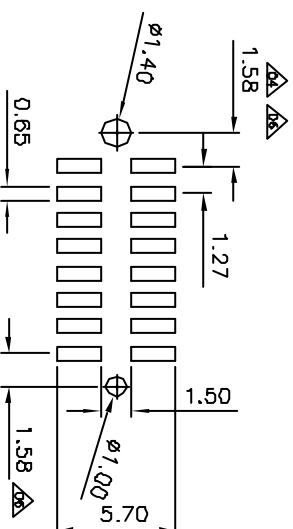
**Operating Temperature:**

Tin plating: -40°C to +105°C  
 Gold plating: -40°C to +105°C

**Materials**

Contact Material: Phosphor Bronze  
 Insulation Material: Polyester, UL 94V-0  
 For 04~25pins, use the plastic material of PA6T, while 26~50pins using LCP.  
 All materials must be GP materials

Recommended P.C.Board  
 Layout  
 (Tolerance: ±0.05)



**Ordering Information**

G SEC202 - XX XX B 01 - X

No. of Pins per Row  
04-50

Contact Plating  
 01=TiN  
 02=Gold Flash  
 Duplex plating  
 05=Gold Flash /TiN

Options  
 P=cap  
 T=tape reel  
 PT=cap+tape reel  
 C=acetate tape  
 TC=acetate tape+tape reel

**GENERAL TOLERANCE**

DESIGN: 黃美君  
 DATE: 2007.05.21

X ± 5.0°

CHECKED: DATE:

X ± 3.0°

AUDITED: DATE:

.XX ± 2.0°

APPROVED: DATE:

.XXX ± 1.0°

DATE:

**格種 股份 有 限 公 司**  
**Greenconn Corporation**

REV. 07 UNIT: mm SCALE: 3:1 PAGE: 1/1

DWG. NO. G SEC202-B01  
 PART NO. G SEC202-XX XX B 01-X

TITLE: 1.27 FEMALE HEADER  
 DUAL ROW SMT TYPE  
 W/POST